

WP9.4 Status

Thomas Bergauer (HEPHY Vienna)





WP9.4 Silicon Tracking

- Creation of a multi-layer micro-strip detector coverage for the calorimeter infrastructure of Task 9.5 to provide a precise entry point of charged particle
 - The calorimeter infrastructure of task 9.5 will be preceded by several layers of Silicon micro-strip detectors to provide a precise entry point over a large area.





WP9.4 Silicon Tracking

- Finely segmented and thin Silicon micro-strip detectors will be designed and procured by the participating institutes [OEAW; IPASCR (CUNI)].
- In the baseline design the system will be read out by electronics developed for the LHC experiments with established performance. [CSIC (IFCA, IFIC, UB)]
- For optimal read-out of long ladders a custom IC with longer shaping time will be developed and validated.
- Part of the ladders will be equipped with realistic services, including cooling, powering, alignment, structural and environmental monitoring.





Current Status

 AIDA is already in Month 13 since its start in February 2011

- Deadlines:
 - Interim Activity Report (due 20th Feb) done.
 - Milestone report documenting deliverable design (due Month 13) TODO!





Requirements from Calorimetry

- What are the expected trigger rates you expect? To be safe, assume that we would record events at a maximum speed of few kHz maximum, although typically we are below a kHz. To saturate DAQ bandwidth, the raw trigger rate could be higher, say 20 kHz.
- What should be the area to cover with silicon? 10x10 cm is rather easy, but anything more makes the project much more expensive. We think that 10x10 cm2 is just sufficient, a bit more (12x12 or 15x15) would give us some safety margin.
- How precise should the entry points in the calorimeter be defined, or, in other words, what
 is the (realistic) resolution you require for that? A sub-millimeter accuracy would be by far
 sufficient. For most studies drift chambers would do, actually. However, for detailed uniformity
 checks more precision would be desirable, and 0.1 mm would cover it all.
- Concerning DAQ integration and data flow: We will provide a TLU style online DAQ synchronization with event numbers stored into our local data stream, which will be converted to LCIO afterwards. Do you also accept TLU input in your DAQ? We foresee to work with the TLU, but we have not exercised it yet, and not all preparations are finished. However, as a working assumption it is OK. Vincent can give more details.





Kick-off meeting Status

Baseline Deliverable

Advanced Deliverable

Two orthogonal layers of u-strips

Provide precise entry point to

Ultra-light strip layer of thin sensors (230 um)

Demonstrator of ILD silicon tracker

HPK SiLC sensors ?

AVP25 based hybrid Conventional mechanics

Integration with CaloDAQ

Offline software

Deliverable

Integrated PA or 2D-Poly silicon or short strip

APV25 based hybrid

Light mechanics with embedded Fiber Optic Sensors

Integration with caloDAQ

Offline Software

ine No dead





SENSORS





Sensors: Baseline Options

- SiLC Sensors from HPK: 6+4 seems to be available at LPNHE Paris (unknown functionality)
- Need to be removed from modules/hybrids and tested afterwards

Inventaire des capteurs Si dans la cage carbone

capteur			
marque	pas de lecture	remarque	carte électronique
HPK	100µ		8VA1
HPK	100µ		8VA1
HPK	100µ		
HPK	50µ	transparent	4VA1
HPK	50µ	transparent	4VA1
HPK	50µ		
HPK	50µ	transparent	4VA1
HPK	100µ		8VA1
HPK	100µ		
HPK	100µ		8VA1







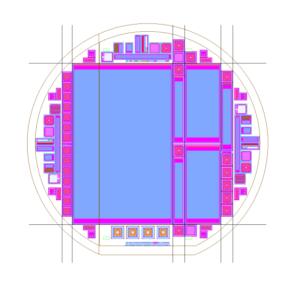


Sensors: Advanced Options

- 2d-sensors from ICFA/CNM:
 - Initial results are very encouraging
 - ICFA has successfully validated a SPICE sensor simulation against the prototype sensors. Will use this simulation to carry out further prototype's optimization



- ON Semi production with IPASCR Prague
 - Sample layout sent to Vaclav Vrba to validate with company
 - "Test the fabrication of large reticles on the present production line by the application of stitching technique"



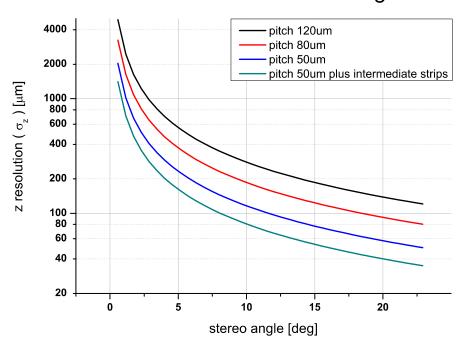




Sensor Pitch and Stereo Angle

- Requirement in resolution ~100 micron
- This equals to 350 micron pitch on sensor (assuming digital readout) in one coordinate
- Stereo Module configuration: very bad resolution with 350 micron pitch and reasonable stereo angle along strips
- Possible scenarios:
 - Use narrow pitch and ~5deg stereo angle
 - Use wide (~350µm) pitch but with orthogonal strips

z resolution vs. stereo angle







ROC AND DAQ





Read-out chip

Baseline: APV25 readout chip

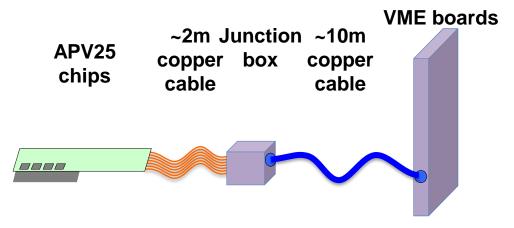
Advanced deliverable: New chip by Barcelona





APV25-based readout systems

- Actually 3 systems for APV25 available
 - APVDAQ system (available in Santander and Vienna)
 - Current Belle-II system (Vienna only)
 - Future Belle-II System (Vienna only starting from 2013)
 - Details on next slide



Front-end hybrids

Rad-hard voltage regulators Analog level translation, data sparsification and hit time reconstruction





Trigger rates for APV-based systems

- APVDAQ:
 - Number of APVs: 4 chips/boards
 - Rate: 1kHz using 1 card (scales with #boards)
 - Advantage: many boards available; more availability for AIDA
- Current Belle-System:
 - 16 APVs/board
 - Rate: 3kHz (Zero Suppressed), 400Hz (raw with 8APVs)
- Future Belle System (currently under development in Vienna):
 - 48APVs/board
 - Rates up to 20kHz
 - Disadvantage: production system for Belle-II; limited availability (i.e. only for one dedicated beam test)





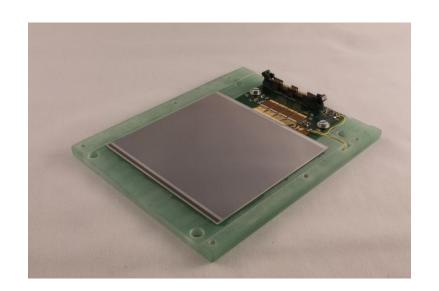
MECHANICS



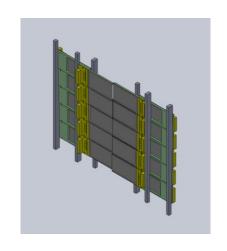


Mechanics: Baseline option

- Simple mechanics made of plastic frame
 - similar to test-beam modules
 - second sensor underneath for stereo



- Stacked arrangement?
 - 2 sensors next to each other (staggered)
 - 2 sensors orthogonal
 - Trigger rates getting down when using APVDAQ system







Mechanics: Advanced Options

- Design of a self-monitoring supporting structure at IFCA
 - made of Carbon-Fiber-Reinforced Polymer (CFRP) composite,
 - equipped with embedded Fiber Bragg Gratings (FBG) sensors for temperature and deformation monitoring.

Status:

- FEA Element mechanical simulation performed of CFRP support
- Next steps: Production of Carbon-Fiber-Reinforced
 Polymer demonstrator equipped with FBG sensors





SOFTWARE





Software

- Integration with CaloDAQ
 - TLU-style synchronization of events
 - Save data to two different data streams

- Offline software
 - HAT software (HEPHY Analysis Toolkit) currently being developed in Vienna
 - Part of it also becomes online part of TuxDAQ
 - LCIO conversion to be used to have common data format among calorimetry and silicon





Schedule for today

- 14:00 Status WP9.4 14:20 Status chip development in UB
- 14:40 Status Vienna
- 15:00 Status CUNI and IPASCR
- 15:20 Status mechanics & environmental sensors
- 15:40 Discussion on Milestone

- Discussion on Milestone report:
 - Basically a summary of the conclusion of this session as few-pages paper